



# From Milliwatts to PFLOPS

GridKa School 2014

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Intel

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# The Path to Discovery & Innovation

## EXPERIMENT

Observation



## THEORY

Mathematical Model

$$\begin{aligned} \frac{\partial u_r}{\partial \theta} + \frac{u_\phi}{r} \frac{\partial u_r}{\partial \phi} - \frac{u_\phi^2 + u_\phi^2}{r} &= -\frac{\partial p}{\partial r} + \rho g_r \\ \frac{1}{\sin(\phi)^2} \frac{\partial^2 u_r}{\partial \theta^2} + \frac{1}{r^2 \sin(\phi)} \frac{\partial}{\partial \phi} \left( \sin(\phi) \frac{\partial u_r}{\partial \phi} \right) - 2 \frac{u_r + \frac{\partial u_\phi}{\partial \theta} + u_\phi}{r^2} \\ \frac{\partial u_\theta}{\partial \theta} + \frac{u_\phi}{r} \frac{\partial u_\theta}{\partial \phi} + \frac{u_r u_\theta + u_\theta u_\phi \cot(\phi)}{r} &= -\frac{1}{r \sin(\phi)} \frac{\partial p}{\partial \theta} + \rho g_\theta \\ \frac{1}{\sin(\phi)^2} \frac{\partial^2 u_\theta}{\partial \theta^2} + \frac{1}{r^2 \sin(\phi)} \frac{\partial}{\partial \phi} \left( \sin(\phi) \frac{\partial u_\theta}{\partial \phi} \right) + \frac{2 \frac{\partial u_r}{\partial \theta} + 2 \cos(\phi)}{r^2 \sin(\phi)} \\ \frac{\partial u_\phi}{\partial \theta} + \frac{u_\phi}{r} \frac{\partial u_\phi}{\partial \phi} + \frac{u_r u_\phi - u_\phi^2 \cot(\phi)}{r} &= -\frac{1}{r} \frac{\partial p}{\partial \phi} + \rho g_\phi \\ \frac{1}{\sin(\phi)^2} \frac{\partial^2 u_\phi}{\partial \theta^2} + \frac{1}{r^2 \sin(\phi)} \frac{\partial}{\partial \phi} \left( \sin(\phi) \frac{\partial u_\phi}{\partial \phi} \right) + \frac{2}{r^2} \frac{\partial u_r}{\partial \phi} - \frac{u_\phi + 1}{r^2} \end{aligned}$$

## HPC

Numerical Simulation



# Performance

it's all about Parallelism

and

Energy Efficiency

# HPC IMPERATIVES

## High Performance

Capabilities & Capacity

## Energy Efficiency

TCO

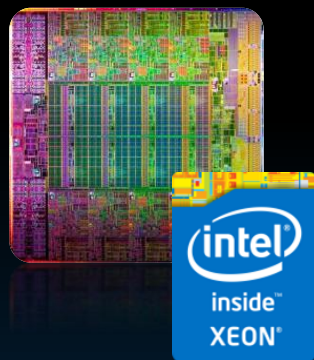
## Ease of Use

Productivity & Sustainability

# Intel's Assets for HPC

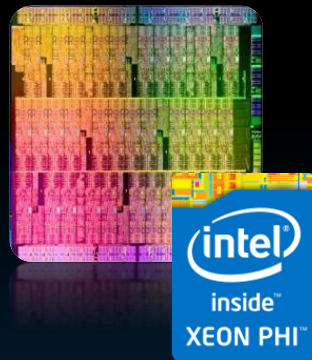
## Processors

Intel® Xeon® Processor



## Coprocessors

Intel® Many Integrated Core



## Network & Fabrics



## Storage



## Software & Services



... and many, many application experts

**Simplicity**  
is the ultimate sophistication.

*- Leonardo da Vinci*

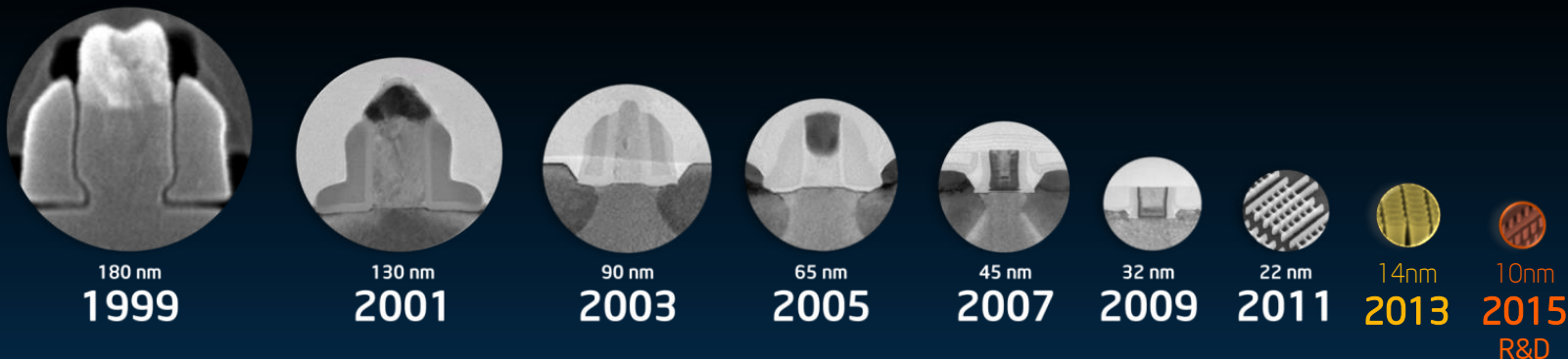


# Transforming the Economics of HPC



## Executing to Moore's Law

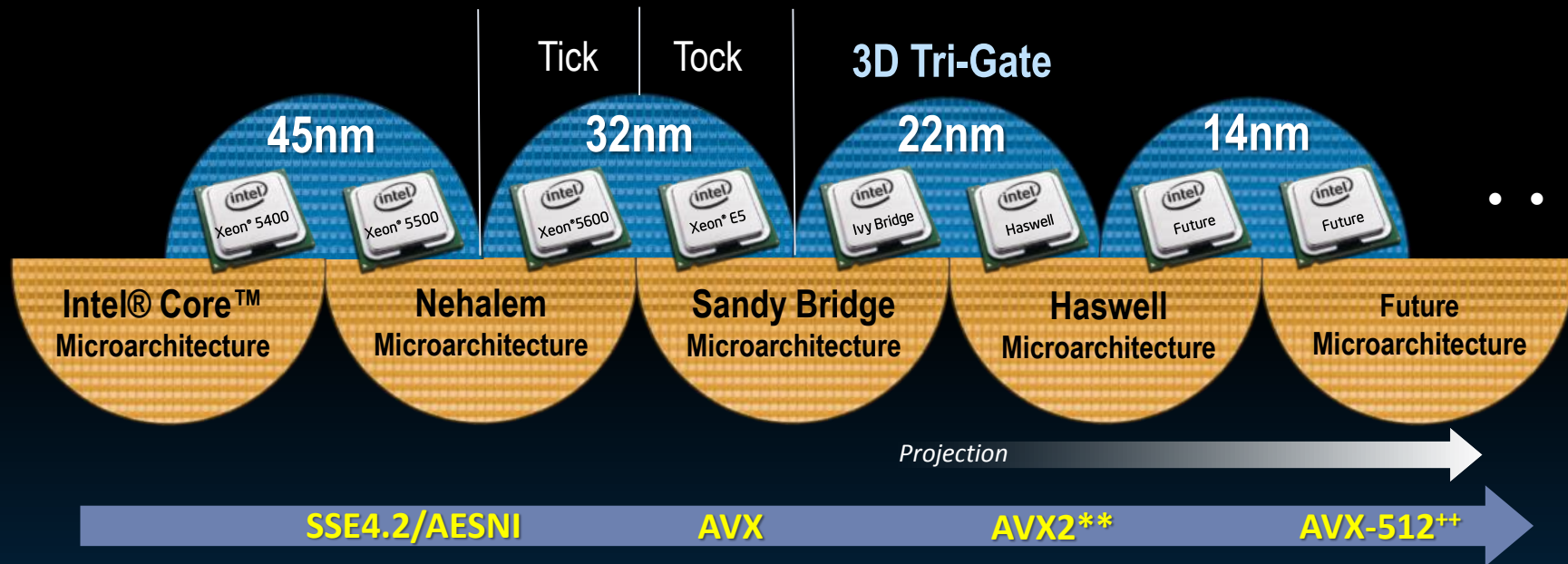
Predictable Silicon Track Record – well and alive at Intel.  
Enabling new devices with higher performance and  
functionality while controlling power, cost, and size



Future options subject to change without notice.

# Tick-Tock Development Cycles

Integrate. Innovate.



\*\*Intel® Architecture Instruction Set Extensions Programming Reference, #319433-012A, FEBRUARY 2012

++Intel® Architecture Instruction Set Extensions Programming Reference, #319433-015, JULY 2013

Potential future options, subject to change without notice.

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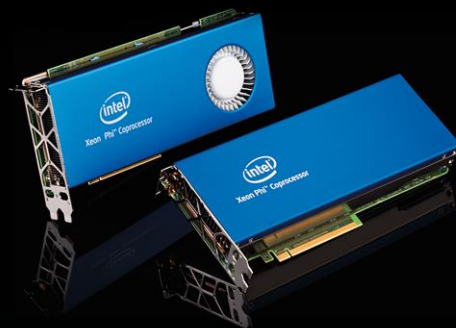
# From MILLIWATTS to TERAFLUPS



Smartphones  
with Intel® Inside



Intel® Xeon®  
Processors

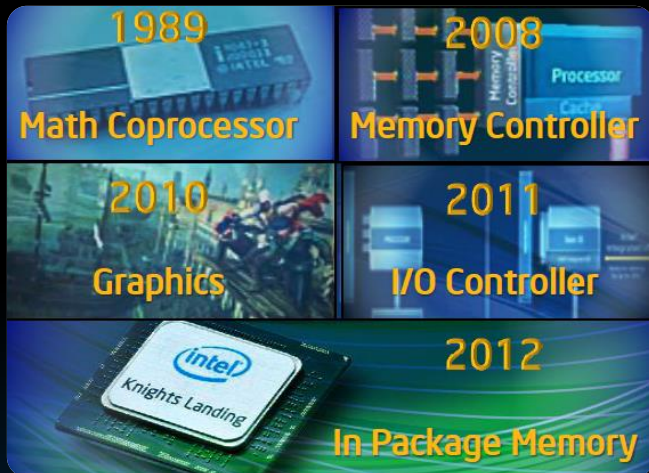


Intel® Many Integrated Core  
Architecture

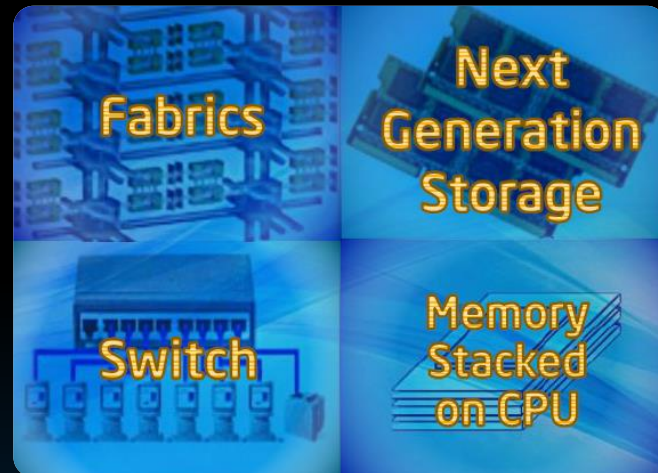
*Energy Efficient*

# Driving Innovation and Integration

Enabled by Leading Edge Process Technologies



Integrated Today

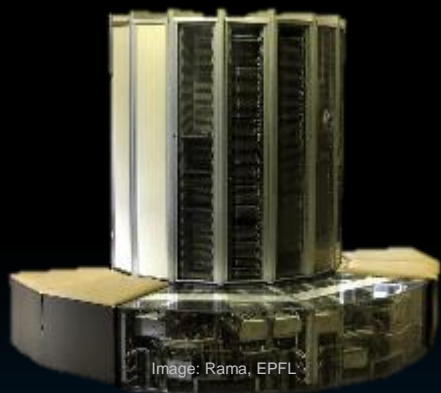


Coming in the Future

SYSTEM LEVEL BENEFITS IN COST, POWER, DENSITY, SCALABILITY & PERFORMANCE

# The Magic of Integration

## Moore's Law at Work & Architecture Innovations



1970s  
**150 MFLOPS**  
CRAY-1

**6666x**



2013  
**1000000 MFLOPS**  
Intel® Xeon Phi™



**#1** TOP500 June 2014

**33** PFLOPS HPL

**54** PFLOPS Peak

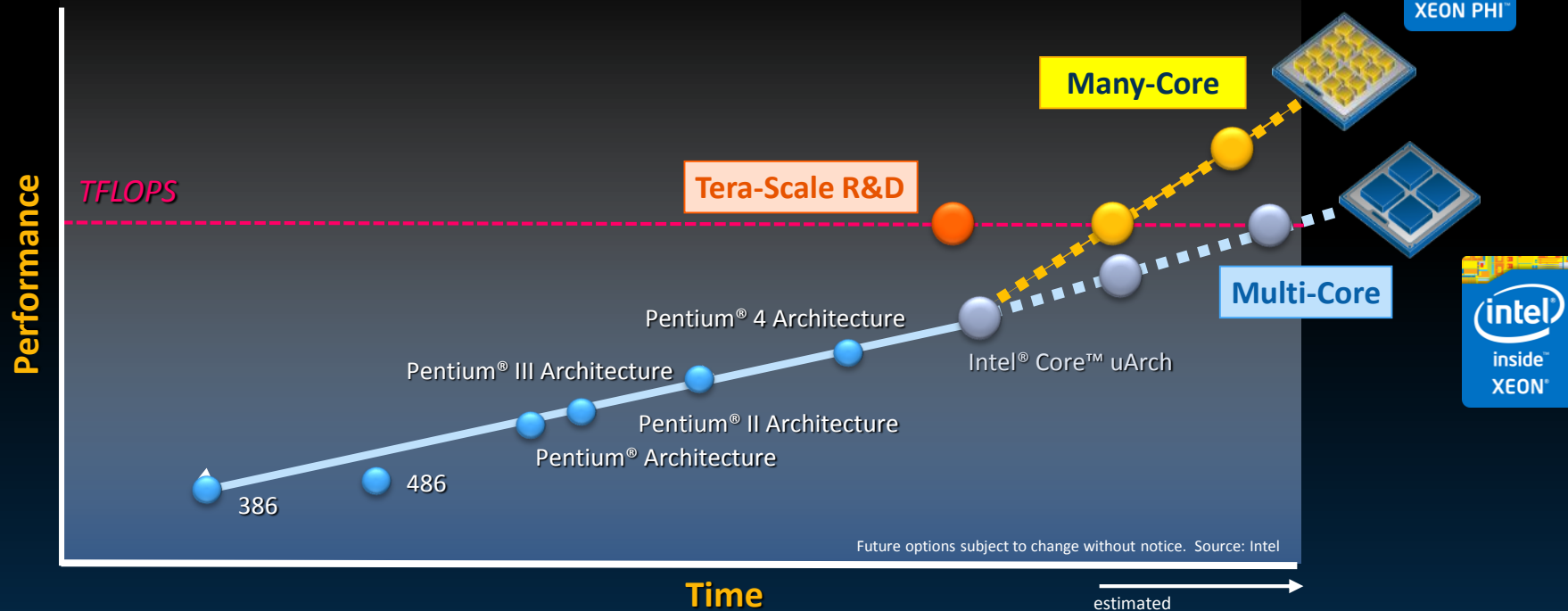
**32000** Intel® Xeon® E5v2 Processors

**48000** Intel® Xeon Phi™ Coprocessors

# Increasing Processor Performance

## Through Many-Core Technologies for Highly Parallel Workloads

**FLOPS/Processor**

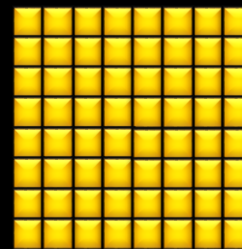


For illustration only. All dates, product descriptions, features, availability, and plans are forecasts and subject to change without notice.

# „Big Core“ – „Small Core“



***Different Optimization Points  
Common Programming Models  
and Architectural Elements***



## **Intel® Xeon® Processor**

Simply aggregating more cores generation after generation is not sufficient

Performance per core/thread must increase each generation, be as fast as possible

Power envelopes should stay flat or go down each generation

Balanced platform (Memory, I/O, Compute)

Cores, Threads, Caches, SIMD

## **Intel® Xeon Phi™ Coprocessor**

Optimized for highest compute per watt

Willing to trade performance per core/thread for aggregate performance

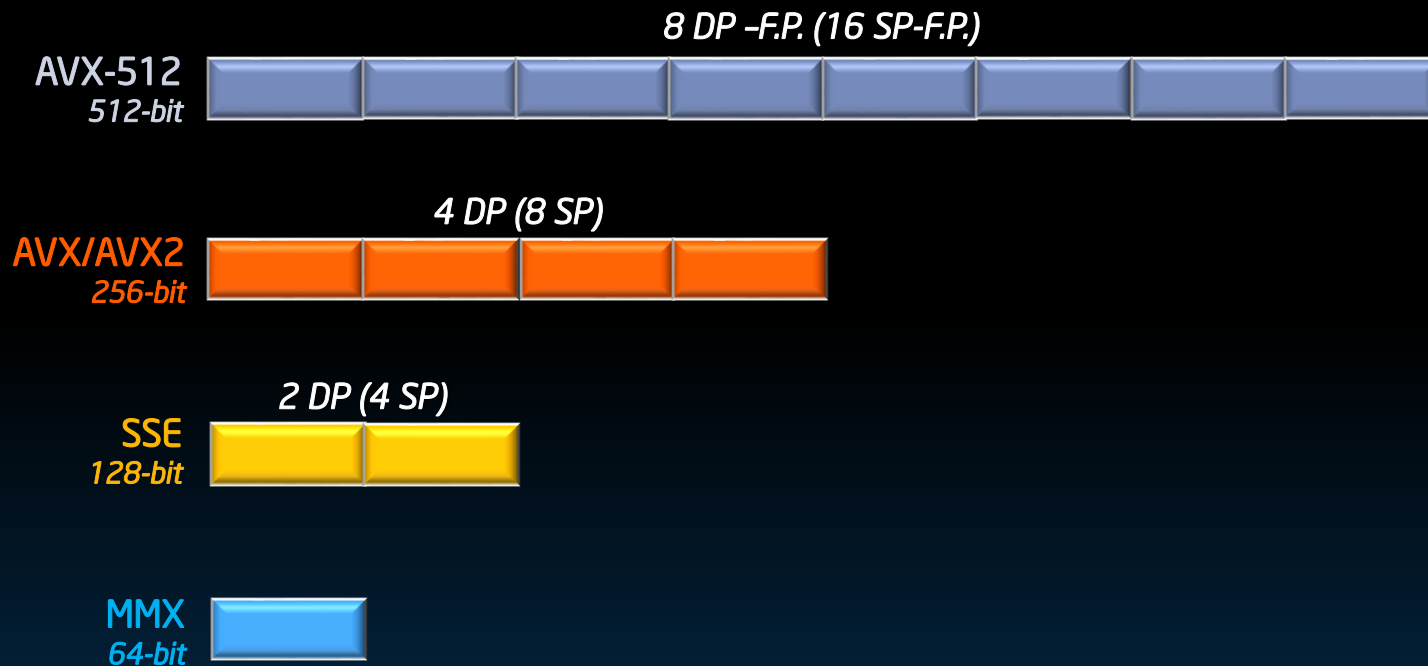
Power envelopes should also stay flat or go down every generation

Optimized for highly parallel workloads

Cores, Threads, Caches, SIMD

For illustration only

# Intel SIMD Evolution



Potential future options and features subject to change without notice.

# Intel Roadmap to Exascale

1.000.000.000.000.000.000

## Intel's Exascale Goal:

Reach Exascale by ~2020 with Intel technologies including Intel® Xeon Phi™ Coprocessors

## Intel® Xeon Phi™ Product Family

### Key ingredient in Intel Exascale Roadmap:

- Programmability
- Power efficiency
- Scalability
- Resiliency



Future options subject to change without notice.

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# Common Programming Models & Software Tools

Common Intel® architecture enables applications to run across the full spectrum of Intel® Xeon® family based servers so programmers don't have to "start over".



Use the same development tools you used for Intel® Xeon® processors, such as Intel® Cluster Studio XE and Intel® Parallel Studio XE

# Intel® Xeon® E5 Processor Family

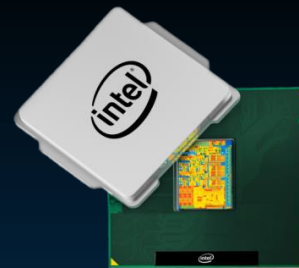
Foundation of HPC Performance  
suited for full scope of workloads

Industry leading performance and  
performance/watt  
for serial & parallel workloads

General purpose with focus on  
fast single core/thread performance  
with “moderate” number of cores



[www.intel.com/xeon](http://www.intel.com/xeon)





[www.intel.com/xeonphi](http://www.intel.com/xeonphi)

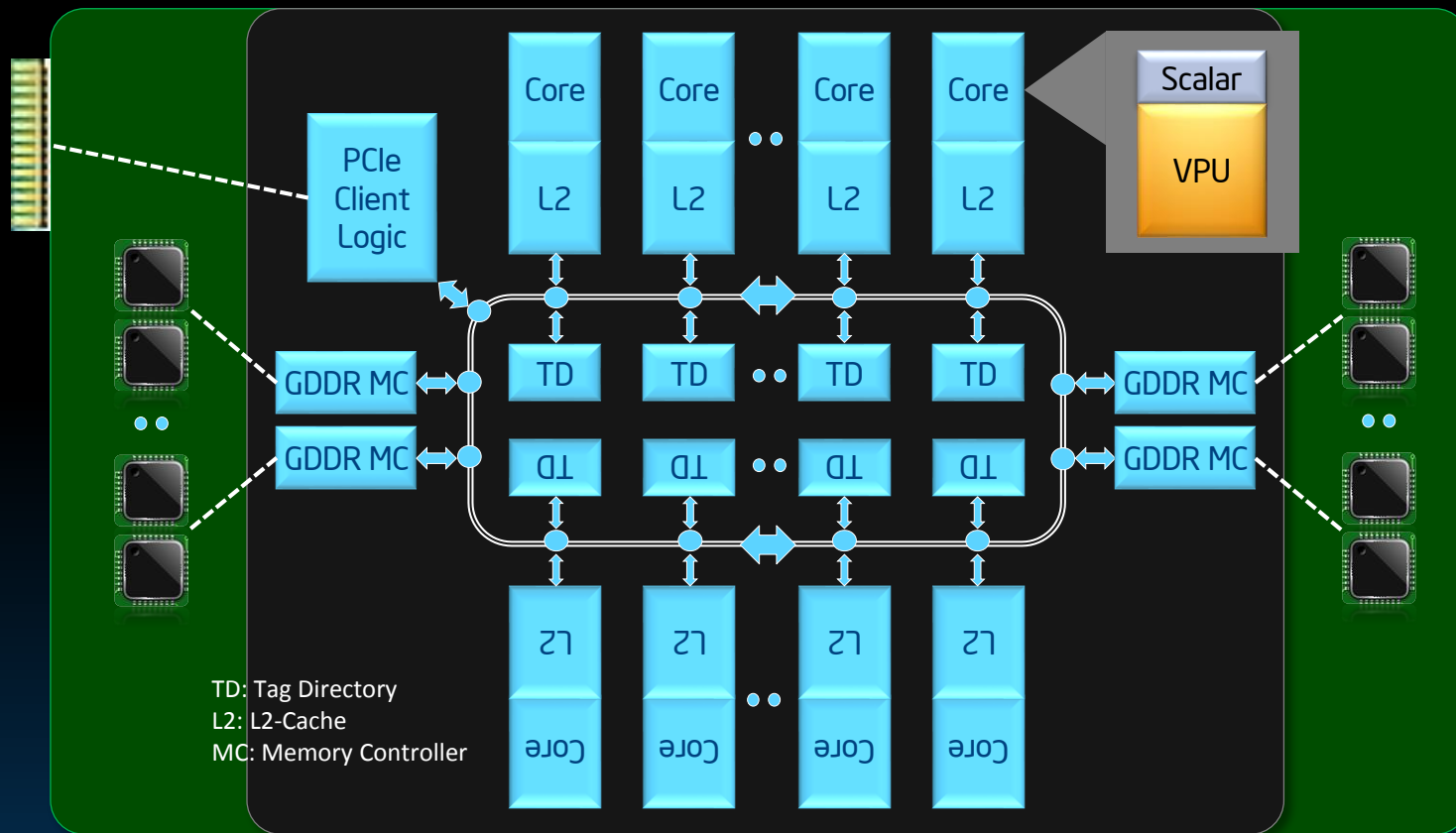


## Intel® Xeon Phi™ Coprocessor

Up to 61 Cores, 244 Threads  
512-bit SIMD instructions  
>1TFLOPS DP-F.P. peak  
Up to 16GB GDDR5 Memory, 352 GB/s  
PCIe\* x16  
Up to 300W TDP (card)

22nm with the world's first  
3-D Tri-Gate transistors  
Linux\* operating system  
IP addressable native node  
Common x86/IA  
Programming Models and SW-Tools

# Intel® Xeon Phi™ Coprocessor Microarchitecture Overview



For illustration only.

# Intel® Xeon Phi™ Coprocessor

Codename: Knights Corner - It is so much more

## Restricted Architectures



Run restricted code

Custom HW Acceleration

## Supercomputer on a chip

Operate as a compute node

Run a full OS (Linux\*)

Run MPI

Run OpenMP\*

Run x86 native code

Run offloaded code



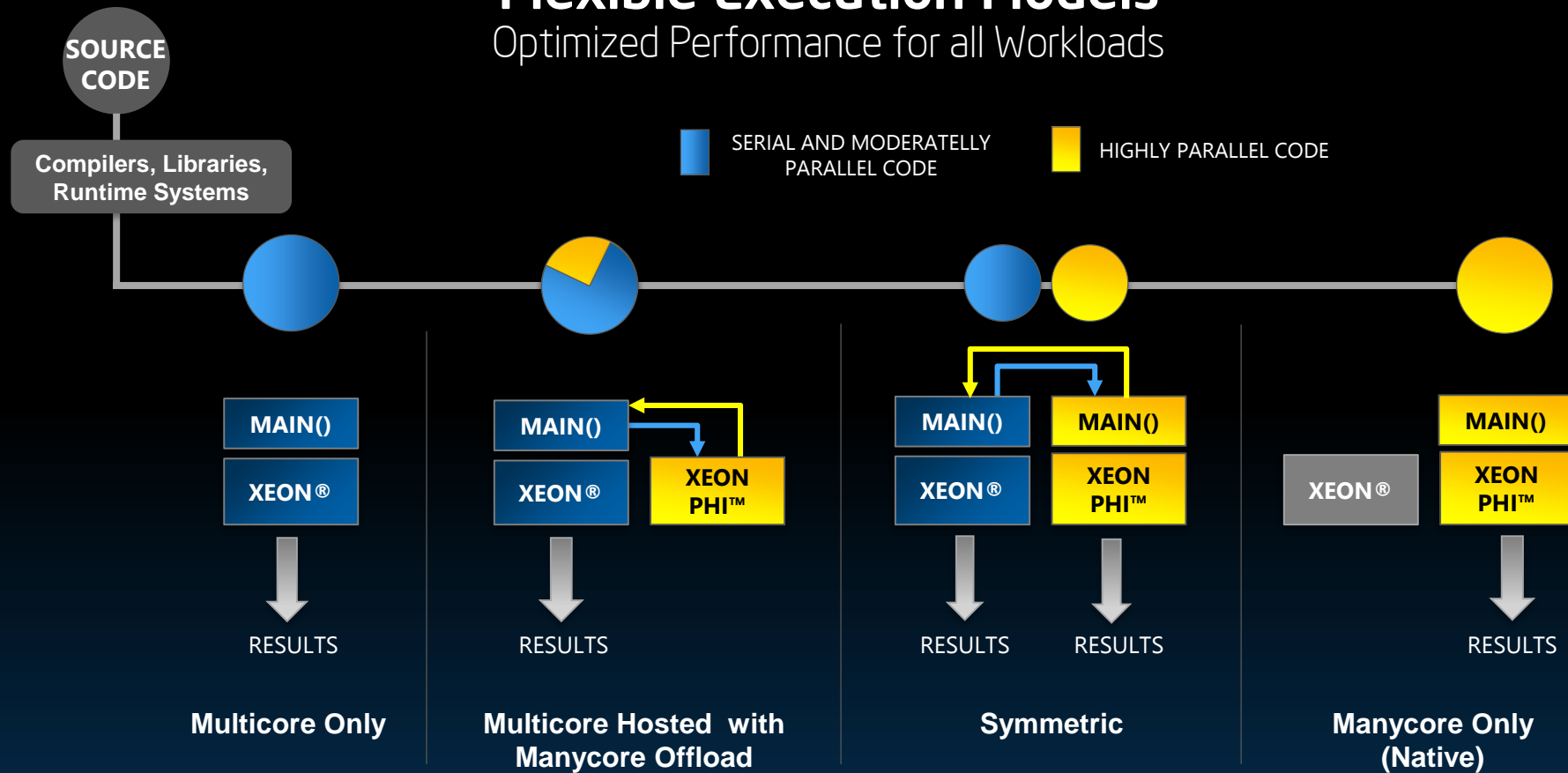
Intel® Xeon Phi™ Coprocessor

Restrictive architectures limit the ability for applications to use arbitrary nested parallelism, functions calls and threading models



# Flexible Execution Models

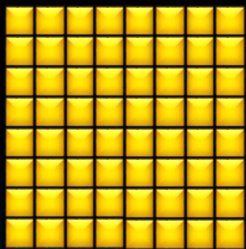
## Optimized Performance for all Workloads



# Manycore Processors – Example HPC Use Cases

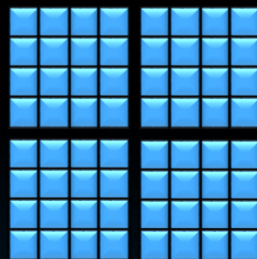
## 1 MPI process

64 Threads each



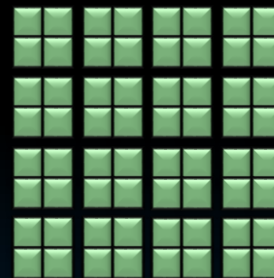
## 4 MPI processes

16 Threads each



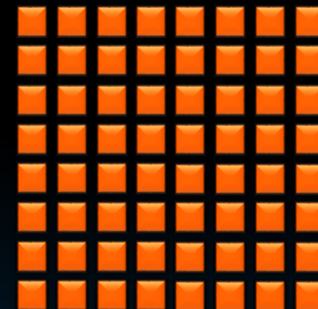
## 16 MPI processes

4 Threads each



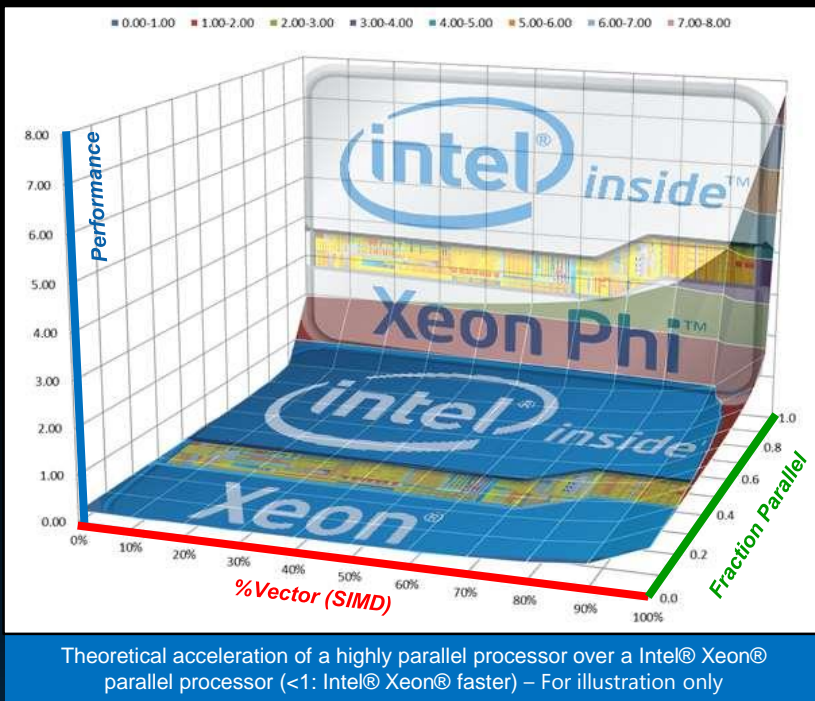
## 64 MPI processes

1 Threads each



For illustration only.

# Highly Parallel Applications



Efficient vectorization, threading, and parallel execution drives higher performance for suitable scalable applications

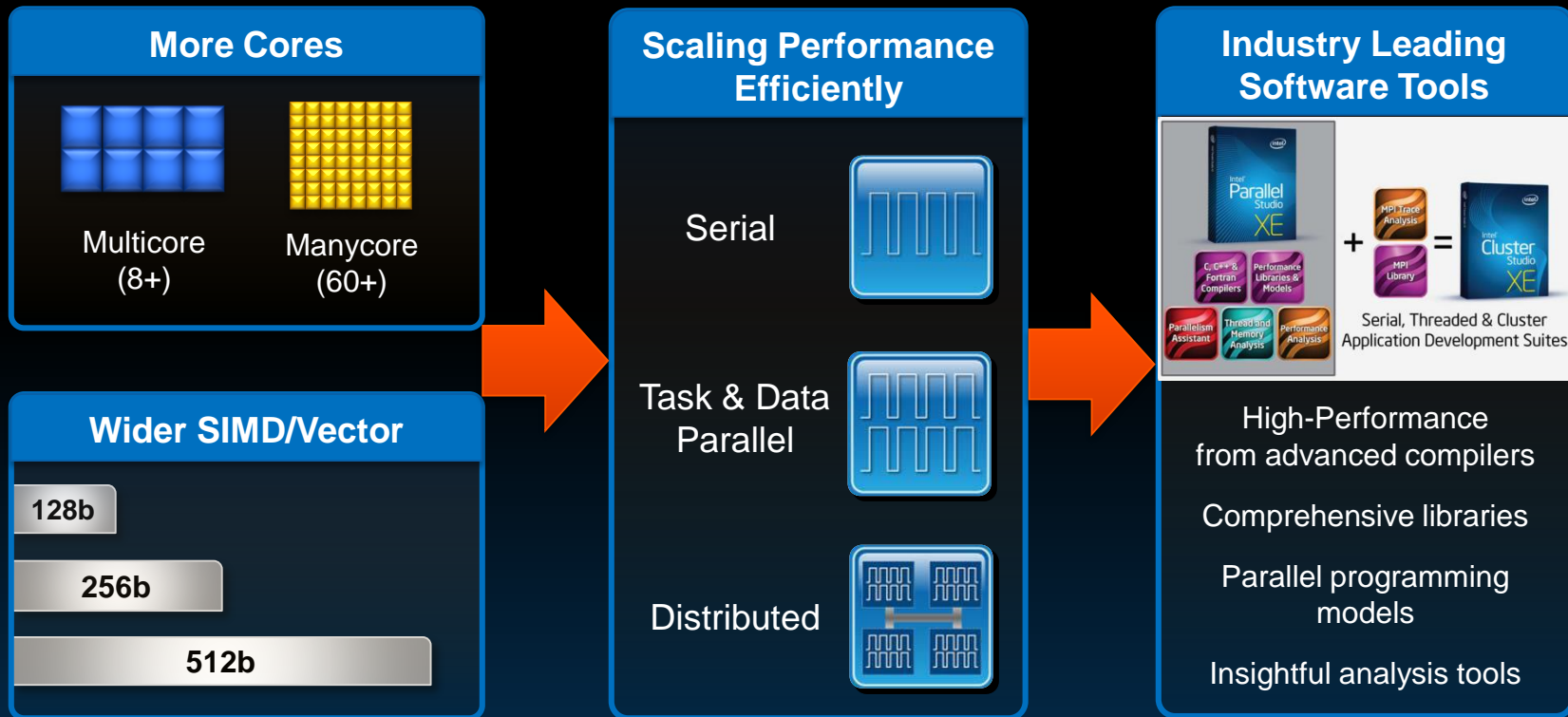
# Parallel Programming for Intel® Architecture (IA)

<b>NODES</b>	Use Intel® MPI, Co-Array Fortran
<b>CORES</b>	Use threads directly or e.g. via OpenMP*, pthreads Use tasking, Intel® TBB / Cilk™ Plus
<b>VECTORS</b>	Intrinsics, auto-vectorization, vector-libraries Language extensions for vector programming (SIMD)
<b>BLOCKING</b>	Use caches to hide memory latency Organize memory access for data reuse
<b>DATA LAYOUT</b>	Structure of arrays facilitates vector loads / stores, unit stride Align data for vector accesses

**Parallel programming to utilize the hardware resources,  
in an abstracted and portable way**

# More Cores. Wider Vectors. Performance Delivered.

Intel® Parallel Studio XE and Intel® Cluster Studio XE



# OpenMP 4.0 Heterogeneous Programming

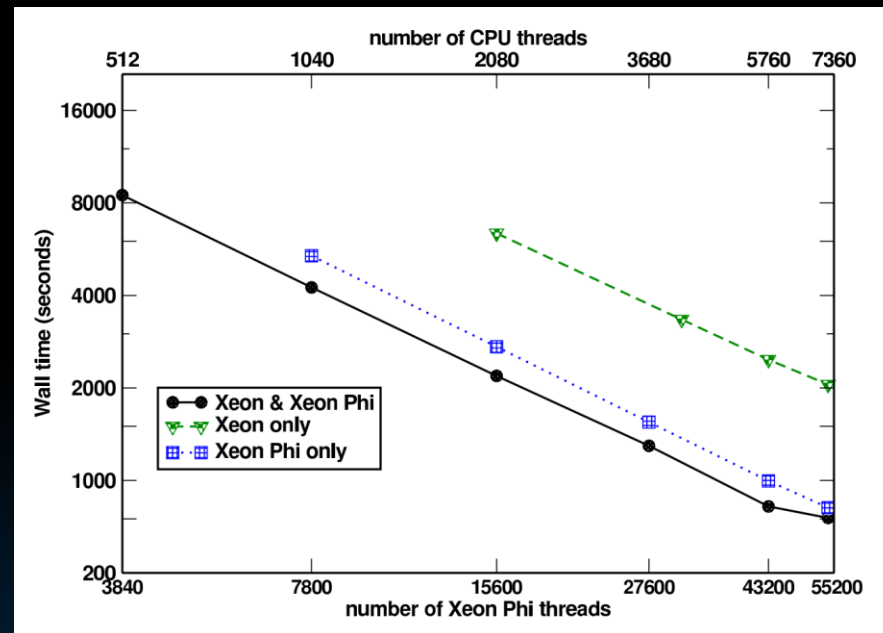
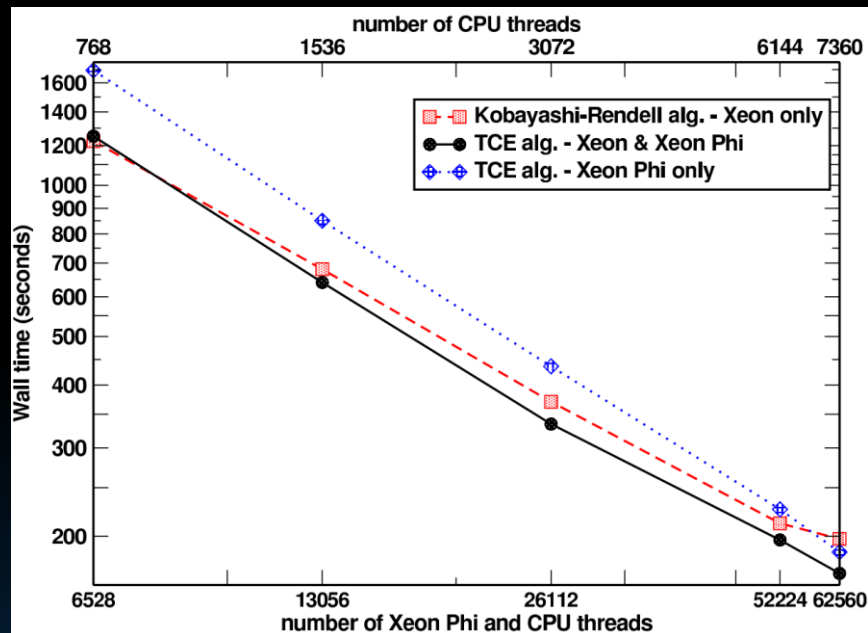
```
#pragma omp target data device(0) map(alloc:tmp[:N]) map(to:input[:N]) map(from:res)
{
#pragma omp target device(0)
#pragma omp parallel for
    for (i=0; i<N; i++)
        tmp[i] = some_computation(input[i], i);

    do_some_other_stuff_on_host();

#pragma omp target device(0)
#pragma omp parallel for reduction(+:res)
    for (i=0; i<N; i++)
        res += final_computation(tmp[i], i)
}
```

host  
target  
host  
target  
host

# Case Study: NWChem CCSD(T) Method



Edoardo Apra, Michael Klemm, and Karol Kowalski. *Efficient Implementation of Many-body Quantum Chemical Methods on the Intel Xeon Phi Coprocessor*. In Proceedings of the International Conference on High Performance Computing, Networking, Storage and Analysis, New Orleans, LA, November 2014. To appear.

Performance tests are measured using specific computer systems, components, software, operations, and functions. Any change to any of those factors may cause the results to vary. You should consult other information and performance tests to assist you in fully evaluating your contemplated purchases, including the performance of that product when combined with other products. System configuration: Atipa Visione vf442 server with two Intel Xeon E5-2670 8-core processors at 2.6 GHz (128 GB DDR3 with 1333 MHz, Scientific Linux release 6.5) and Intel C600 IOH, two Intel Xeon Phi coprocessors 5110P (GDDR5 with 3.6 GT/sec, driver v3.1.2-1, flash image/micro OS 2.1.02.0390, Intel Composer XE 14.0.1.106).

# Next Intel® Xeon Phi™ Processor

Codename: **Knights Landing**



Designed using Intel's cutting-edge  
**14nm process**

Not bound by "offloading" bottlenecks  
**Standalone CPU**  
**or PCIe Coprocessor**

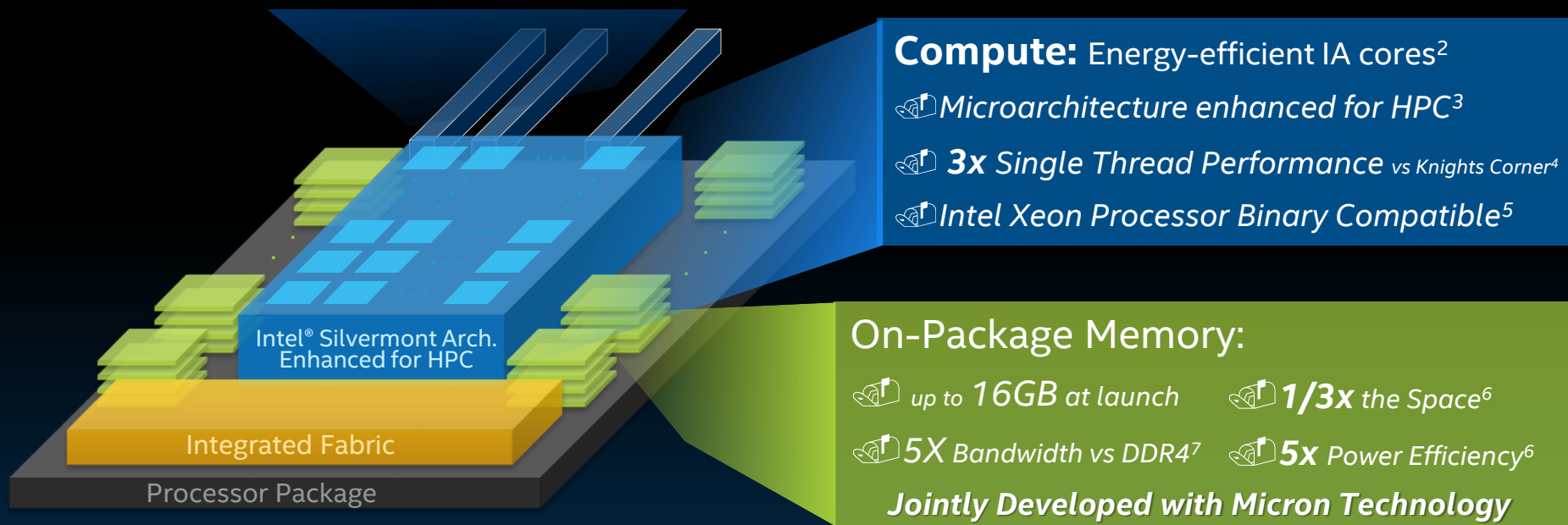
Leadership compute & memory bandwidth  
**Integrated**  
**On-Package Memory**

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# Next Intel® Xeon Phi™ Processor

Codename: **Knights Landing**

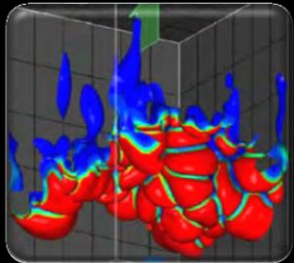


A blue-tinted, artistic illustration of three historical figures. On the left is a Native American man with a large feathered headdress. In the center is a European man with a beard and a crown. On the right is an East Asian man with a beard and a traditional cap. The background is a textured, smoky blue.

# Journey to Exascale

# Assume Exascale Computing at 20MW ...

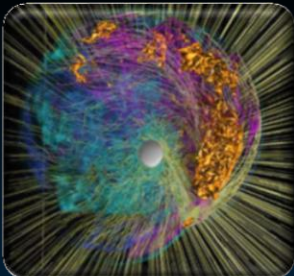
## New Forms of Energy



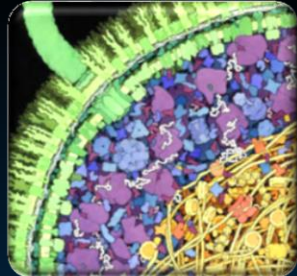
## Ecological Sustainability



## Space Exploration



## Medical Innovation



*And many others....*

1 Exaflop

**20MW**

1 Petaflop

**20KW**

*Today's #25 system  
in a rack!*

1 Teraflop

**20W**

*100x the performance  
of today's phone at the  
same power*

1 Gigaflop

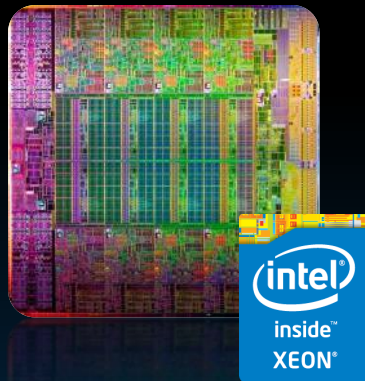
**20mW**

For illustration and concept only.

# HPC: *The Path to Exascale*

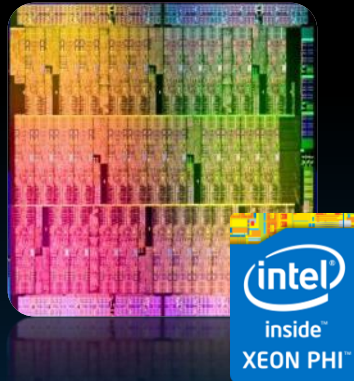
## Processors

Intel® Xeon® Processor

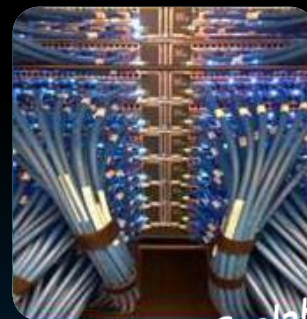


## Coprocessor

Intel® Many Integrated Core



## Fabrics



*Scalability*

## Software



# HPC:

## *The Path to Exascale (cont.)*

### Memory & Storage



### Networking



### Reliability & Resiliency



### Power Management

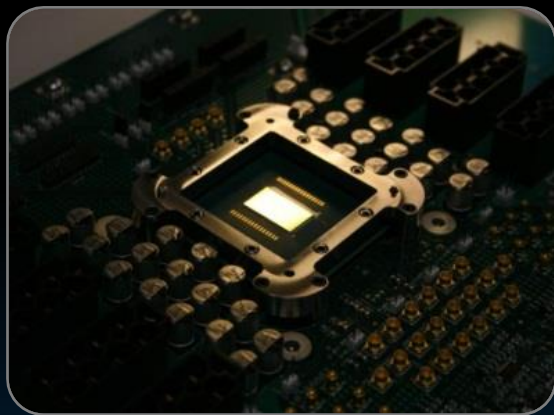


Energy  
Efficiency



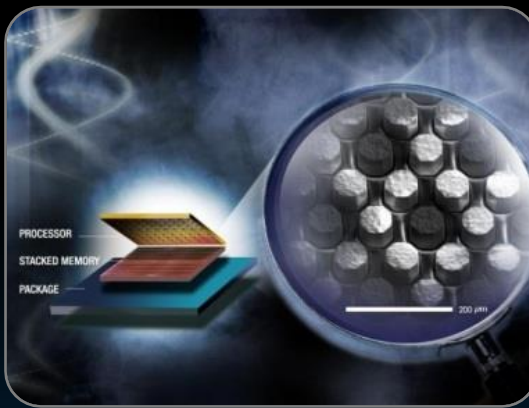
# Intel TeraScale Research Areas

## MANY-CORE COMPUTING



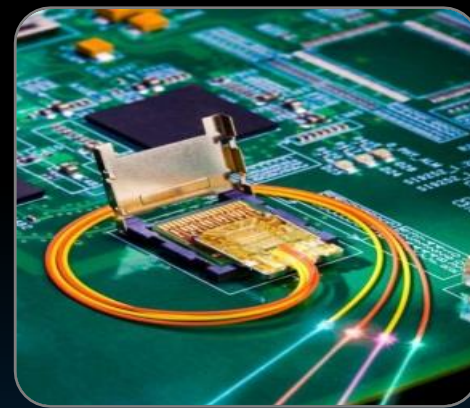
**Teraflops**  
of computing power

## STACKED MEMORY



**Terabytes**  
of memory bandwidth

## SILICON PHOTONICS



**Terabits**  
of I/O throughput

Future vision, does not represent real products.

# The Power of Solutions: Big Data Example

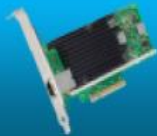
Sort 1 TB of Data:  
**>4 Hours**



Intel® Xeon®  
E5-2690 processor



Intel® SSD  
520 series



Intel® 10GbE  
adapters

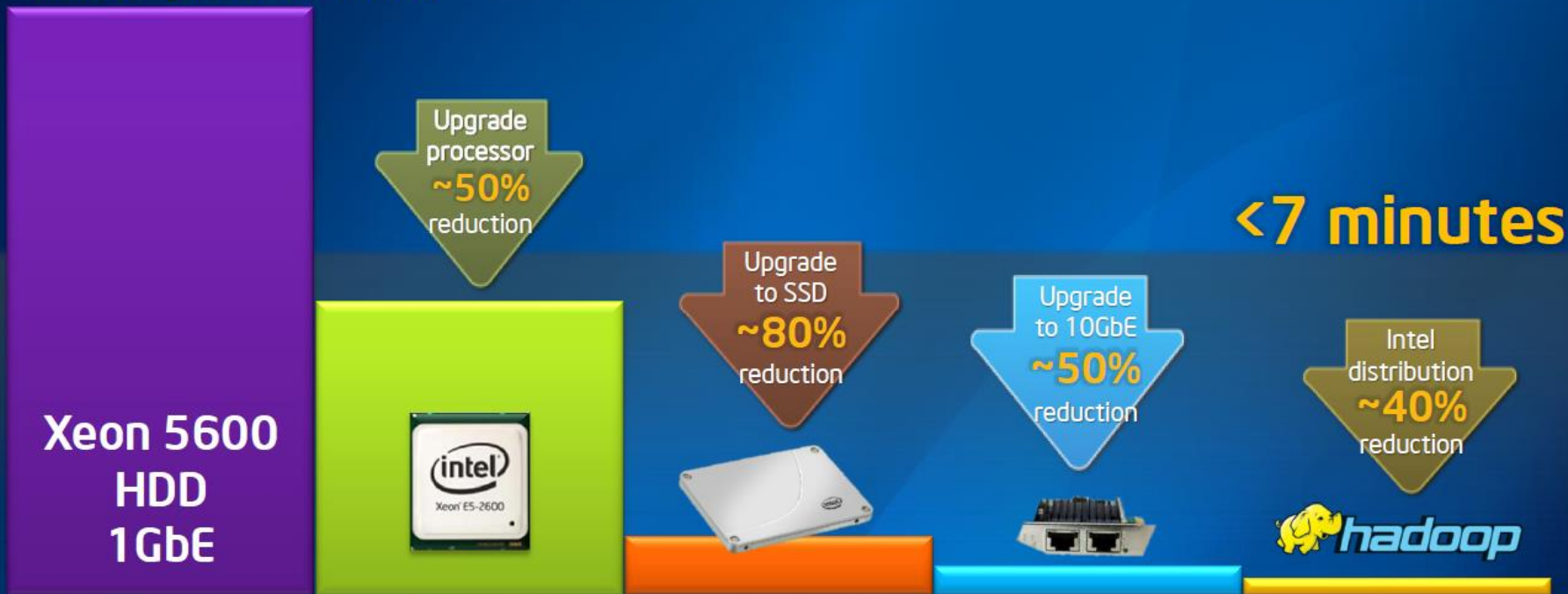


Intel® Distribution  
for Apache Hadoop\*

Sort 1 TB of Data:  
**7 MINUTES**

# The Power of Platform Solutions

TeraSort for 1TB sort:  
**>4 hour process time**





# PERFORMANCE

it's all about **SCALABLE** parallelism

## THINK PARALLEL!

INTEL  
INNOVATION & LEADERSHIP  
FOR THE ROAD AHEAD

**Thank You.**

